measurement area and the actual position of the DUT, and therefore, the storage state of the DUT may not be correctly determined. In the electronic component handling apparatus described above, when a pocket in which a DUT is not accommodated exists in the DUT container, the pick-and-place device may stop due to the pocket. Further, when the DUT is accommodated in a pocket of the DUT container in a tilted state, or when two DUTs are accommodated in one pocket in an overlapping manner, the pick-and-place device may damage the DUT.

[0005] The problems to be solved by the present disclosure are to provide an electronic component handling apparatus capable of reducing the damage of the improvement and DUT operating rate, and, an electronic component testing apparatus having the electronic component handling apparatus.

[0006] [1] An electronic component handling apparatus according to an aspect of the present disclosure is an electronic component handling apparatus that handles a DUT, the electronic component handling apparatus comprising: a chamber that applies thermal stress to the DUT; an acquiring device that acquires three-dimensional shape data of a DUT container having a plurality of accommodating portions capable of accommodating the DUT in a state where the DUT container is heated; a first correcting device that calculates a first correction amount from the shape data and corrects the shape data based on the first correction amount; an extracting device that extracts a height and/or a slope of a predetermined region corresponding to the DUT in the accommodation portion from the shape data corrected by the first correcting device; and a determining device that determines an accommodation state of the DUT in the accommodation portion based on an extraction result of the extracting device, wherein the first correction amount represents a movement amount and/or a rotation amount in a planar direction of the shape